NEC

BIPOLAR DIGITAL INTEGRATED CIRCUIT

μPB1504GR

1.1 GHz LOW-POWER TWO-MODULUS PRESCALER ÷64/65, ÷128/129 FOR MOBILE TELEPHONE

DESCRIPTION

μPB1504GR is a 64/65, 128/129 two modulus prescaler to construct pulse swallow type PLL frequency synthesizer for 800 MHz to 900 MHz mobile telephone. This IC is manufactured using latest high speed bipolar process. This process reduces stray capacitance of internal transistor and wirings to achieve low current consumption. For this reason, μPB1504GR is suitable for battery-operated telephone systems.

FEATURES

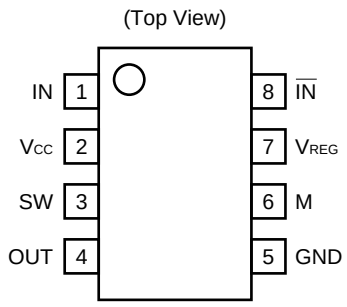
- High toggle frequency : 0.5 GHz to 1.1 GHz
- Supply voltage : V_{CC} = V_{RFG} = 2.7 to 3.6 V
- Low current consumption : 2.4 $mA_{TYP.}$ @3.3 V spec. (1.9 $mA_{TYP.}$ @3.0 V reference data)
- Palse swallow control : ÷64/65, ÷128/129
- High input frequency : –19 dBm to +4 dBm

ORDER INFORMATION

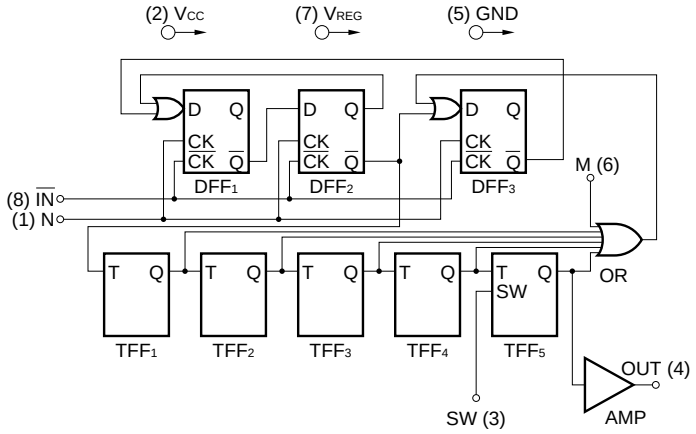
ORDER NUMBER	PACKAGE	SUPPLYING FORM
μPB1504GR-E1	8 pin plastic SOP (225 mil)	Embossed tape 12 mm wide. QTY 2.5 k/reel Pin 1 is in tape pull-out direction.
μPB1504GR-E2		Embossed tape 12 mm wide. QTY 2.5 k/reel Pin 1 is in tape roll-in direction.

Remarks To order evaluation samples, please contact your local NEC sales office.
(Order number: μPB1504GR)

PIN ASSIGNMENT



INTERNAL BLOCK DIAGRAM



Caution: Electro-static sensitive devices

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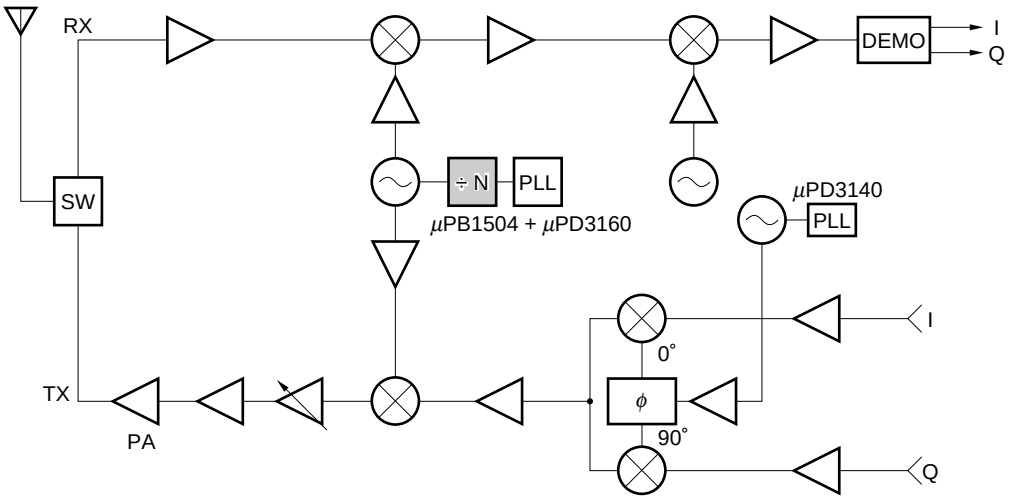
SELECTOR GUIDE

TYPE	PART NUMBER	DIVIDE RATIO	V_{CC} (V)	I_{CC} (mA)	f_{in} (GHz)	V_{in} (dBm)	PACKAGE
1.1 GHz	μPB1504GR	64/65, 128/129	2.7 to 3.6	2.4	0.5 to 1.1	–19 to +4	8 pin SOP
1.7 GHZ	μPB1502GR	64/65, 128/129	2.7 to 3.3	6.7	0.5 to 1.7	–15 to –6	8 pin SOP
2.0 GHz	μPB1502GR(1)	64/65, 128/129	2.7 to 3.3	6.7	0.5 to 2.0	–15 to –1	8 pin SOP

Note The above table lists the typical performance to compare similar ICs. Please refer to ELECTRIC CHARACTERISTICS of each IC's data sheet.

SYSTEM APPLICATION EXAMPLE

Digital cellular phone



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATINGS	UNIT	CONDITIONS
Supply Voltage	V_{CC}	–0.5 to +4.5	V	T_A = +25 ˚C
Regulator Pin Bias	V_{REG}	0 to V_{CC}	V	T_A = +25 ˚C
Input Voltage	V_{IN}	–0.5 to V_{CC}	V	T_A = +25 ˚C
Power Dissipation	P_D	250	mW	Mounted on double sided copper clad 50 × 50 × 1.6 mm epoxy glass PWB at T_A = +85 ˚C
Storage Temperature	T_{STG}	–55 to +125	˚C	

RECOMMMENDED OPERATING RANGE

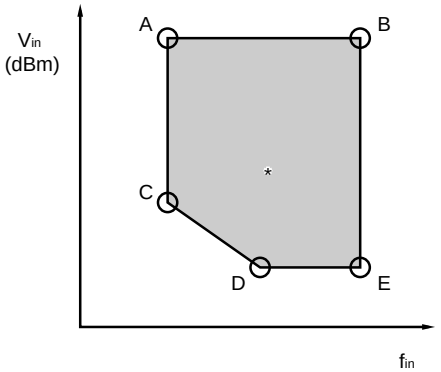
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage	V_{CC}	2.7	3.0	3.6	V
Regulator Pin Bias	V_{REG}	2.7	V_{CC}	V_{CC}	V
Output Load Capacitance	C_L	—	—	10	pF
Operation Temperature	T_A	–30	—	+85	˚C

ELECTRICAL CHARACTERISTICS

(V_{CC} = V_{REG} = 2.7 to 3.6 V, T_A = –30 to +85 ˚C; Unless otherwise specified)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Circuit Current @÷64/65	I_{CC}	—	2.47	3.22	mA	V_{CC} = V_{REG} = 3.3 V T_A = +25 ˚C No input signals
Circuit Current @÷128/129		—	2.24	2.93		
Output Voltage Swing	V_O	0.65	0.9	—	V_{P-P}	fin = 1.1 GHz
Response Input frequency	f_{in}	0.5	—	1.1	GHz	CL = 10 pF
Input Power Sensitivity	V_{in}	–19	—	+4	dBm	fin = 800 MHz to 1.1 GHz
		–14	—	+4		fin = 500 MHz
Modulus Control Input High	V_{IH}	0.8 V_{CC}	—	—	V	6 pin (M)
Modulus Control Input Low	V_{IL}	—	—	0.2 V_{CC}	V	
Divide Ratio Control Input High	V_{IH}	V_{CC}			V	3 pin (SW)
Divide Ratio Control Input Low	V_{IL}	OPEN			V	
Modulus Setup Time	t_{SET}	—	27	33	ns	÷ 64/65, CL = 10 pF

NOTICE: Following figure shows relation between RESPONSE INPUT FREQUENCY and INPUT POWER SENSITIVITY



f_{in} V_{in}

A : (500 MHz, +4 dBm)

B : (1.1 GHz, +4 dBm)

C : (500 MHz, –14 dBm)

D : (800 MHz, –19 dBm)

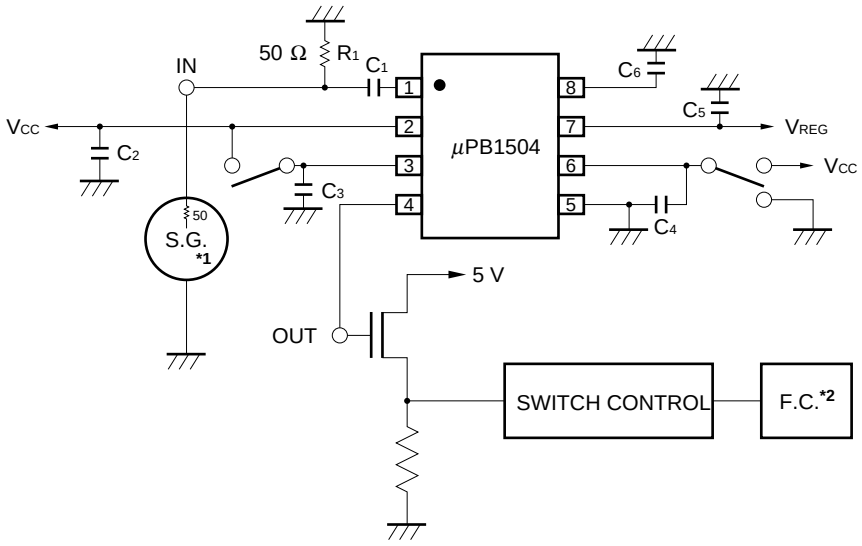
E : (1.1 GHz, –19 dBm)

* Guaranteed Operating Window

PIN DESCRIPTIONS

<table>
<tr><th>PIN NO.</th><th>SYMBOL</th><th>ASSIGNMENT</th><th>FUNCTIONS AND EXPLANATION</th></tr>
<tr><td>1</td><td>IN</td><td>Frequency input pin</td><td>Input frequency from an external VCO output.
Must be coupled with capacitor (e.g. 1 000 pF) for DC cut.</td></tr>
<tr><td>2</td><td>V_{CC}</td><td>Power supply pin</td><td>Supply voltage 2.7 to 3.6 V for operation. Must be connected bypass capacitor (e.g. 1 000 pF) to minimize ground impedance.</td></tr>
<tr><td>3</td><td>SW</td><td>Divided ratio control input pin</td><td rowspan="2">Divided ratio and modulus control can be governed by following input data to these pins.
<table><tr><td colspan="2"></td><td colspan="2">M</td></tr><tr><td colspan="2"></td><td>H</td><td>L</td></tr><tr><td rowspan="2">SW</td><td>H</td><td>1/64</td><td>1/65</td></tr><tr><td>L</td><td>1/128</td><td>1/129</td></tr></table></td></tr>
<tr><td>6</td><td>M</td><td>Modulus control input pin (pulse swallow control pin)</td></tr>
<tr><td>4</td><td>OUT</td><td>Divided frequency output pin</td><td>This frequency output can be interfaced to CMOS PLL, because of 0.65 Vp-p $_{MIN.}$ output swing on high-impedance. This output triggers with negative edge.</td></tr>
<tr><td>5</td><td>GND</td><td>Ground pin</td><td>Must be connected to the system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. (Track length should be kept as short as possible).</td></tr>
<tr><td>7</td><td>V_{REG}</td><td>Regulator bias pin</td><td>This pin controls regulator circuit. Relation between supply bias and operation is shown below.
<table><tr><td colspan="2"></td><td>Operation</td></tr><tr><td rowspan="2">V_{REG}</td><td>H</td><td>ON</td></tr><tr><td>L</td><td>OFF</td></tr></table></td></tr>
<tr><td>8</td><td>$\overline{IN}$</td><td>Frequency-input bypass input</td><td>Must be connected bypass capacitor (e.g. 1 000 pF) to minimize ground impedance.</td></tr>
</table>

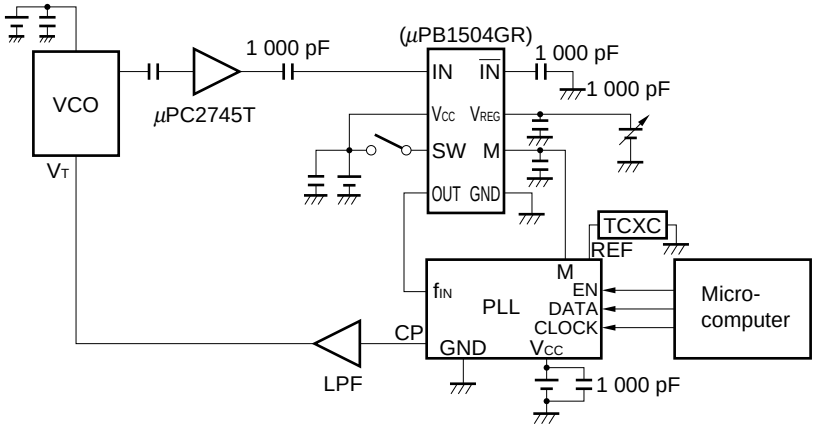
TEST CIRCUIT



SYNTHESIZDE SIGNAL SOURCE *1

MICROWARE FREQUENCY COUNTER *2

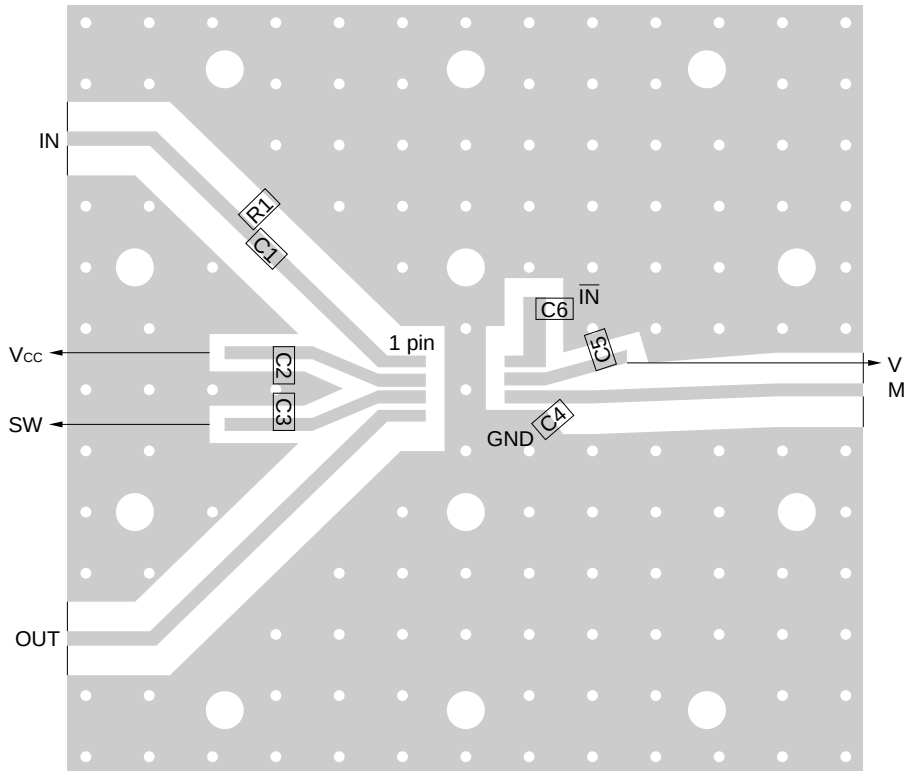
SCHEMATIC EXAMPLE FOR APPLICATION OF μPB1504GR



The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

To know the real application circuits, please refer to PLL synthesizer LSI's documentations (e.g. μPD3160GS).

TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD



COMMENT LIST

No.	Value
C1 to 6	1 000 pF
R1	50 Ω

Note (*1) 50 × 50 × 0.4 mm double copper clad polyimide board

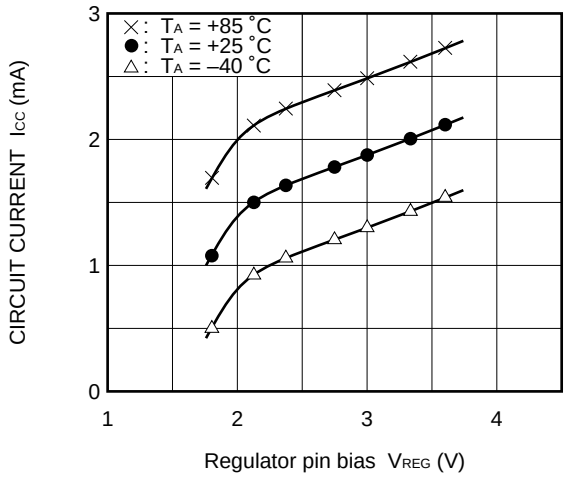
(*2) Backside: GND

(*3) Solder plated on pattern

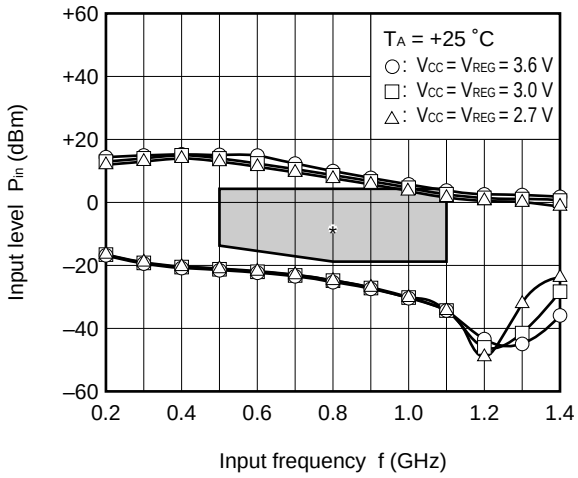
(*4) ○◯: Through holes

TYPICAL CHARACTERISTICS

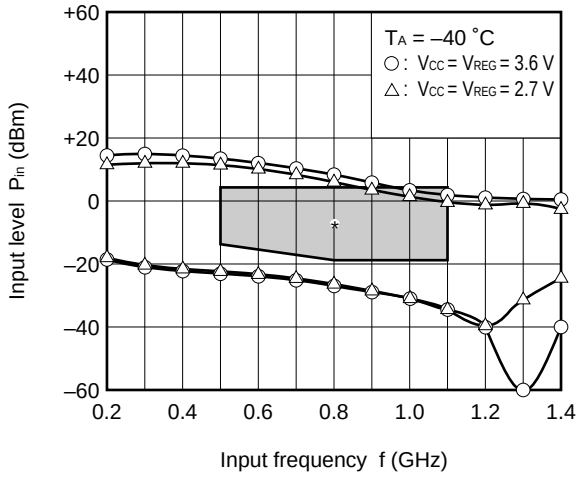
CIRCUIT CURRENT vs. REGULATOR VOLTAGE (V_{CC} = 3 V)



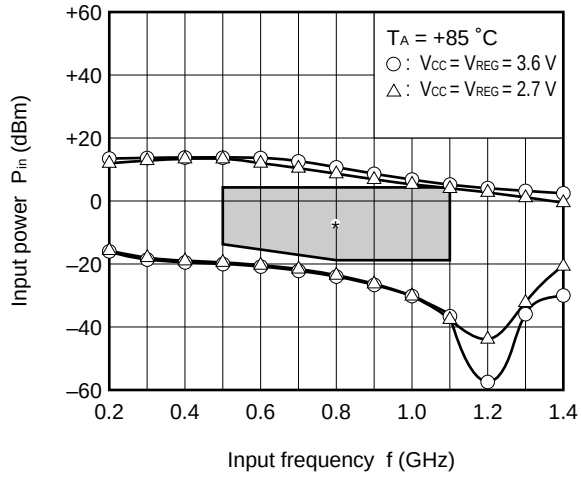
INPUT POWER vs. FREQUENCY



INPUT POWER vs. FREQUENCY

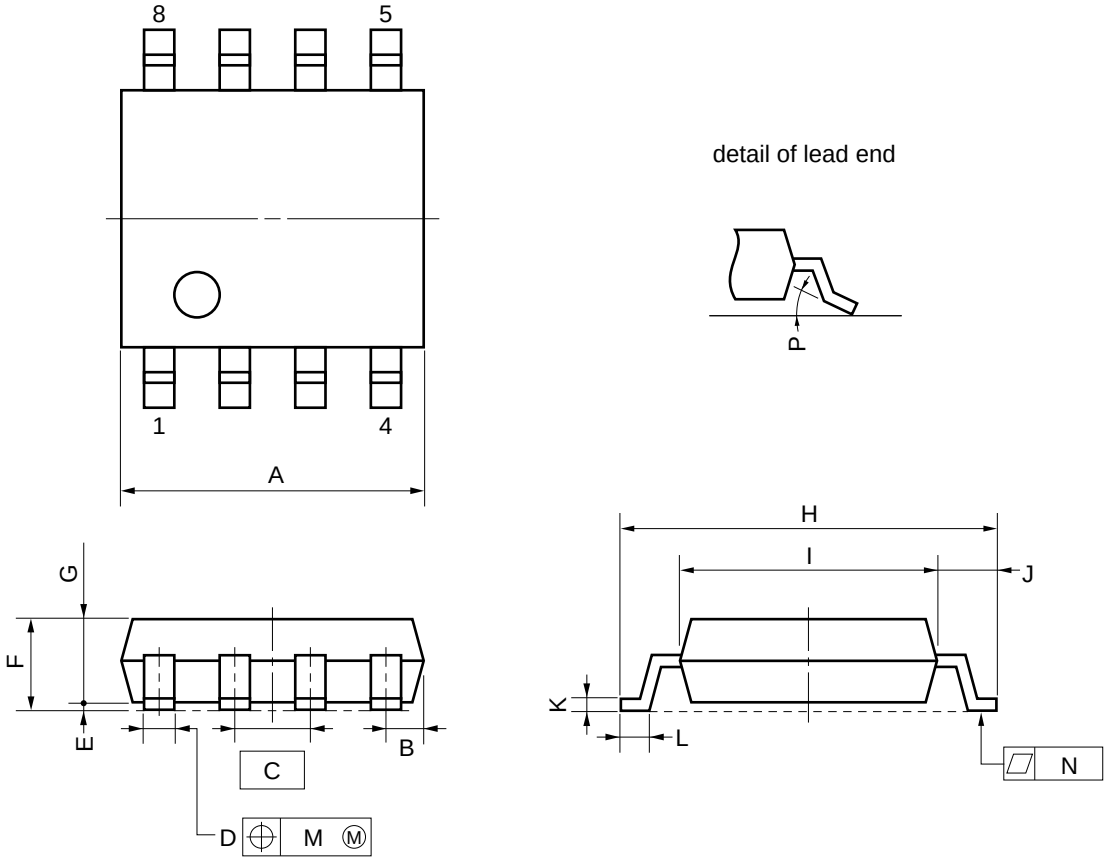


INPUT POWER vs. FREQUENCY



* Guaranteed Operating Window

8 PIN PLASTIC SOP (225 mil)



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	5.37 MAX.	0.212 MAX.
B	0.78 MAX.	0.031 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	$0.40^{+0.10}_{-0.05}$	$0.016^{+0.004}_{-0.003}$
E	0.1±0.1	0.004±0.004
F	1.8 MAX.	0.071 MAX.
G	1.49	0.059
H	6.5±0.3	0.256±0.012
I	4.4	0.173
J	1.1	0.043
K	$0.15^{+0.10}_{-0.05}$	$0.006^{+0.004}_{-0.002}$
L	0.6±0.2	$0.024^{+0.008}_{-0.009}$
M	0.12	0.005
N	0.10	0.004
P	$3°^{+7°}_{-3°}$	$3°^{+7°}_{-3°}$

S8GM-50-225B-4

NOTE ON CURRENT USE

(1) Observe precautions for handling because of electro-static sensitive devices.
(2) Form a ground pattern as wide as possible to minimize ground impedance (to prevent undesired operation).
(3) Keep the wiring length of the ground pins as short as possible.
(4) Connect a bypass capacitor (e.g. 1 000 pF) to the V_{CC} pin.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered in the following recommended conditions. Other soldering methods and conditions than the recommended conditions are to be consulted with our sales representatives.

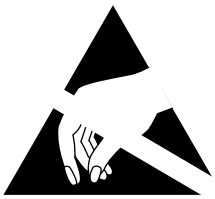
μPB1504GR

SOLDERING METHOD	SOLDERING CONDITIONS	RECOMMENDED CONDITION SYMBOL
Infrared ray reflow	Package peak temperature: 230 ˚C, Hour: within 30 s. (more than 210 ˚C), Time: 2 times, Limited days: no.*	IR30-00-2
VPS	Package peak temperature: 215 ˚C, Hour: within 40 s. (more than 200 ˚C), Time: 1 time, Limited days: no.*	VP15-00-1
Wave soldering	Soldering tub temperature: less than 260 ˚C, Hour: within 10 s. Time: 1 time, Limited days: no.	WS60-00-1
Pin part heating	Pin are temperature: less than 300 ˚C, Hour: within 2 s. Limited days: no.*	

*: It is the storage days after opening a dry pack, the storage conditions are 25 ˚C, less than 65 % RH.

Note The combined use of soldering method is to be avoided (However, except the pin area heating method)

For details of recommended soldering conditions for surface mounting, refer to information document SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL (C10535EJ7V0IF00).



ATTENTION

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
SENSITIVE
DEVICES

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